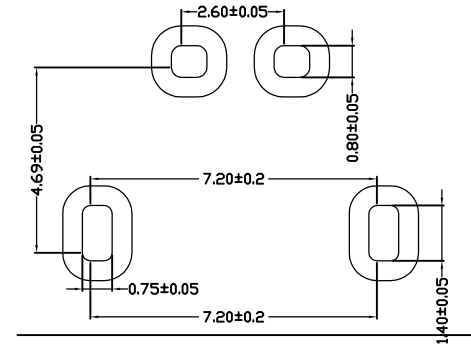
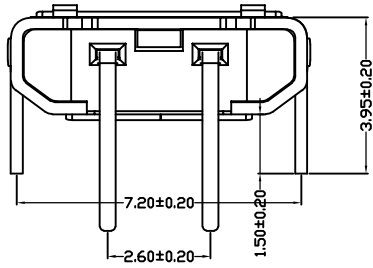
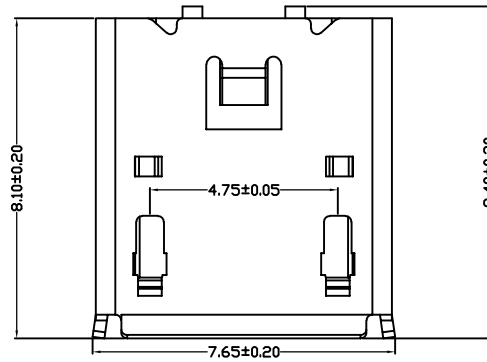
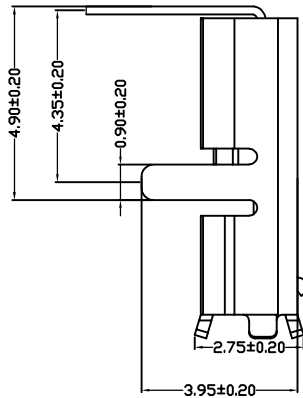
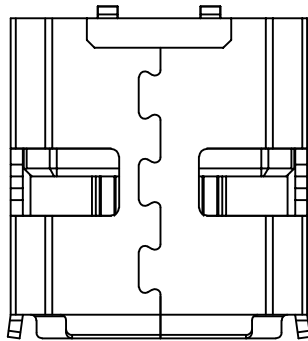


修改序号	修改说明	签名	日期
A/0			



PCB LAYOUT



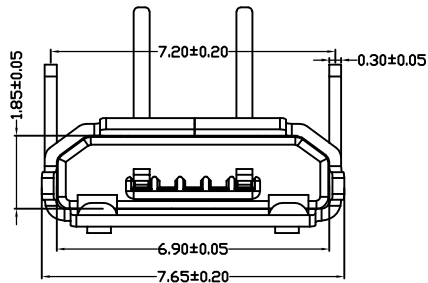
Note:

1. Material:

- 1.1 Housing: High temperature thermoplastic with g.f, UL94v-0
- 1.2 Contact: copper alloy,  $t=0.20\text{mm}$
- 1.3 Shell: SPCC  $t=0.3\text{mm}$  or SUS  $t=0.25$

2. Specification:

- 2.1 Current rating: 1A Max
- 2.2 Dielectric withstanding voltage: 100V(AC) for 1 min.
- 2.3 Contact resistance:  $40\text{m}\Omega$  Max.
- 2.4 Insulation resistance:  $100\text{M}\Omega$  min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 1500 or 10,000 insertion/extraction cycles
- 2.7 Temperature range:  $-30^{\circ}\text{C}\sim 80^{\circ}\text{C}$



尺寸	允许公差
.X	$\pm 0.50$
.X	$\pm 0.20$
.XX	$\pm 0.10$
.XXX	$\pm 0.03$
角度	$\pm 1.00^{\circ}$

深圳市创勤科技有限公司  
Shenzhen Chuangqin Technology Co., Ltd.

图纸类型		图纸名称:	
产品工程图		MICRO USB BF 2P DIP7.2(1.5*0.9)插板	
设计	LIN YUN	2011.07.21	产品料号
审核			CQ028-MFLT20151001
		视图	版号: A/0

